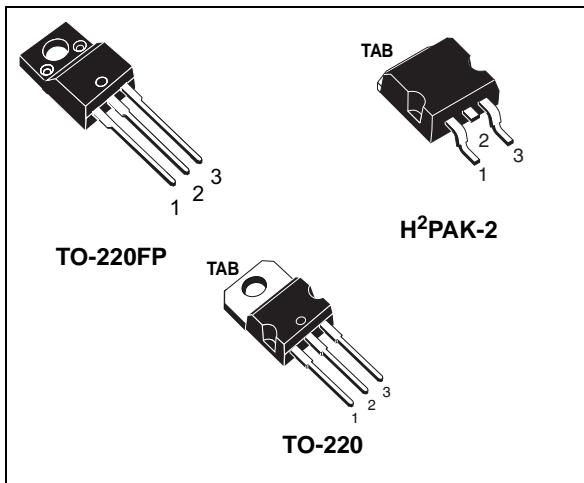
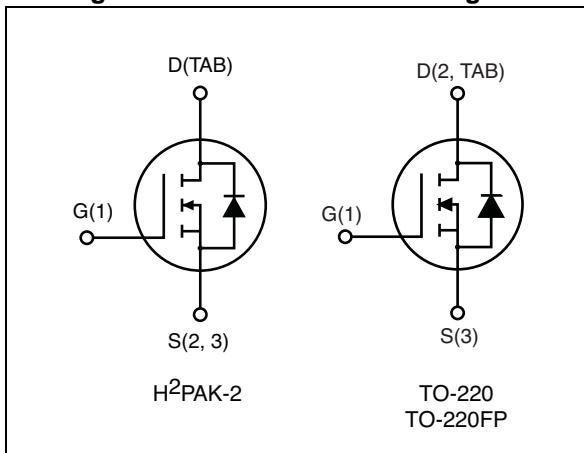


N-channel 80 V, 3.3 mΩ typ., 90 A STripFET™ VII DeepGATE™ Power MOSFET in TO-220FP, H<sup>2</sup>PAK-2 and TO-220 packages

Datasheet - production data



**Figure 1. Internal schematic diagram**



## Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>	P <sub>TOT</sub>
STF140N8F7	80 V	4.3 mΩ	64 A	35 W
STH140N8F7-2	80 V	4 mΩ	90 A	200 W
STP140N8F7	80 V	4.3 mΩ	90 A	200 W

- Ultra low on-resistance
- 100% avalanche tested

## Applications

- Switching applications

## Description

These devices are N-channel Power MOSFETs developed using the 7<sup>th</sup> generation of STripFET™ DeepGATE™ technology, with a new gate structure. The resulting Power MOSFETs exhibits the lowest R<sub>DS(on)</sub> in all packages.

**Table 1. Device summary**

Order code	Marking	Package	Packaging
STF140N8F7	140N8F7	TO-220FP	Tube
STH140N8F7-2		H <sup>2</sup> PAK-2	Tape and reel
STP140N8F7		TO-220	Tube

## Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		TO-220 H <sup>2</sup> PAK-2	TO-220FP	
$V_{DS}$	Drain-source voltage	80		V
$V_{GS}$	Gate-source voltage	$\pm 20$		
$I_D$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	90 <sup>(1)</sup>	64 <sup>(2)</sup>	A
$I_D$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	90 <sup>(1)</sup>	45 <sup>(2)</sup>	
$I_{DM}^{(3)}$	Drain current (pulsed)	360	256	
$P_{TOT}^{(2)}$	Total dissipation at $T_C = 25^\circ\text{C}$	200	35	W
$E_{AS}^{(4)}$	Single pulse avalanche energy	515		mJ
$T_j$	Operating junction temperature	- 55 to 175		°C
$T_{stg}$	Storage temperature			

1. Limited by package
2. This value is rated according to  $R_{thj-c}$
3. Pulse width is limited by safe operating area
4. Starting  $T_j = 25^\circ\text{C}$ ,  $I_d = 18.5 \text{ A}$ ,  $V_{dd} = 50 \text{ V}$

**Table 3. Thermal data**

Symbol	Parameter	Value			Unit
		TO-220FP	TO-220	H <sup>2</sup> PAK-2	
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb			35	°C/W
$R_{thj-case}$	Thermal resistance junction-case	4.29	0.75		°C/W
$R_{thj-amb}$	thermal resistance junction-ambient	62.5			°C/W

1. When mounted on FR-4 board of 1inch<sup>2</sup>, 2oz Cu, t < 10 sec

## 2 Electrical characteristics

( $T_{CASE} = 25^\circ\text{C}$  unless otherwise specified)

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage ( $V_{GS} = 0$ )	$I_D = 250 \mu\text{A}$	80			V
$I_{DSS}$	Zero gate voltage Drain current ( $V_{GS} = 0$ )	$V_{DS} = 80 \text{ V}$ $V_{DS} = 80 \text{ V}, T_J=125^\circ\text{C}$			1 10	$\mu\text{A}$
$I_{GSS}$	Gate-source leakage current ( $V_{DS} = 0$ )	$V_{GS} = 20 \text{ V}$			100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2.5		4.5	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	For TO-220FP: $V_{GS} = 10 \text{ V}, I_D = 32 \text{ A}$		3.5	4.3	$\text{m}\Omega$
		For H <sup>2</sup> PAK-2: $V_{GS}=10 \text{ V}, I_D = 45 \text{ A}$		3.3	4	
		For TO-220: $V_{GS}=10 \text{ V}, I_D = 45 \text{ A}$		3.5	4.3	

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 40 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0$	-	6340	-	$\text{pF}$
$C_{oss}$	Output capacitance			1195		
$C_{rss}$	Reverse transfer capacitance			105		
$Q_g$	Total gate charge	$V_{DD} = 40 \text{ V}, I_D = 64 \text{ A}, V_{GS} = 10 \text{ V}$	-	96	-	$\text{nC}$
$Q_{gs}$	Gate-source charge			30		
$Q_{gd}$	Gate-drain charge			26		

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 40 \text{ V}, I_D = 45 \text{ A}$ $R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	26	-	$\text{ns}$
$t_r$	Rise time			51		
$t_{d(off)}$	Turn-off-delay time			82		
$t_f$	Fall time			44		

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current	For H <sup>2</sup> PAK-2 and TO-220 For TO-220FP	-		90 64	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)	For H <sup>2</sup> PAK-2 and TO-220 For TO-220FP	-		360 256	
$V_{SD}^{(2)}$	Forward on voltage	For TO-220FP: $I_{SD} = 64 \text{ A}, V_{GS} = 0$ For TO-220, H <sup>2</sup> PAK-2: $I_{SD} = 90 \text{ A}, V_{GS} = 0$	-		1.2	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 64 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$ $V_{DD} = 60 \text{ V}$ $T_j = 150^\circ\text{C}$	-	58		ns
$Q_{rr}$	Reverse recovery charge		-	92		nC
$I_{RRM}$	Reverse recovery current		-	3.2		A

1. Pulse width is limited by safe operating area  
 2. Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-220FP

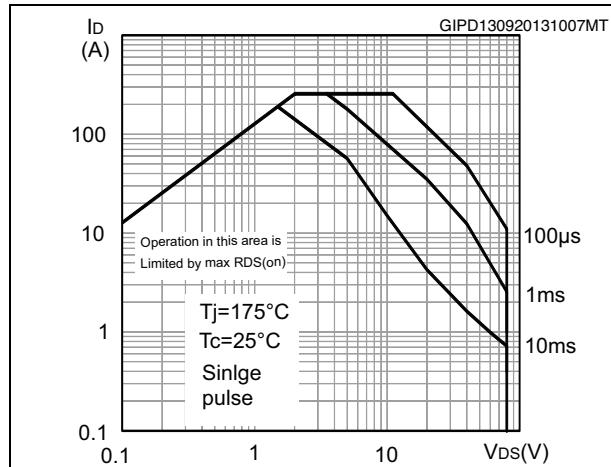


Figure 3. Thermal impedance for TO-220FP

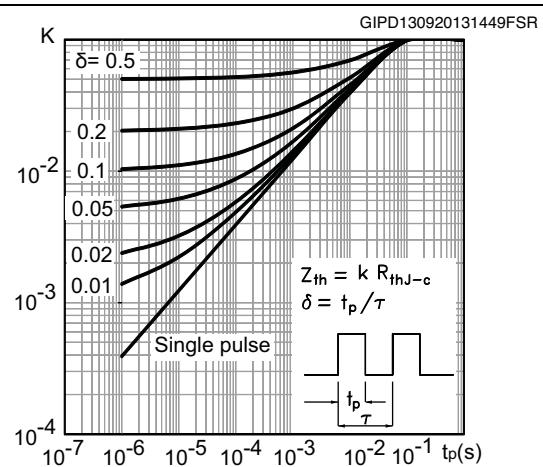
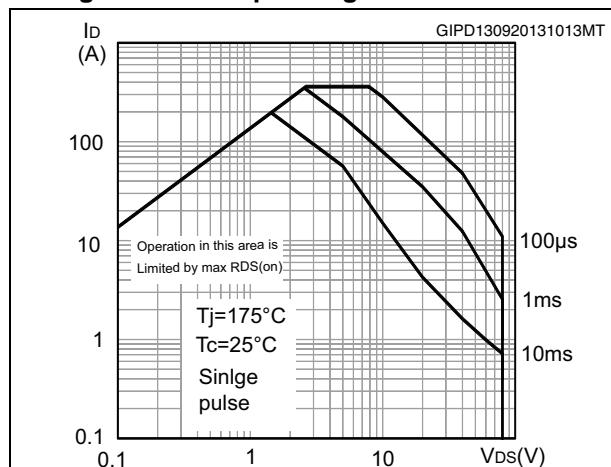
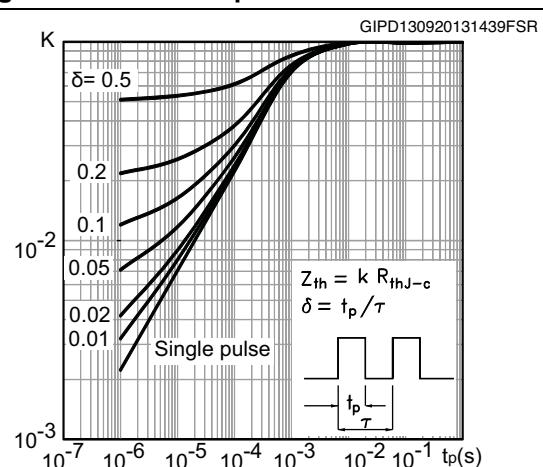
Figure 4. Safe operating area for H<sup>2</sup>PAK-2Figure 5. Thermal impedance for H<sup>2</sup>PAK-2

Figure 6. Safe operating area for TO-220

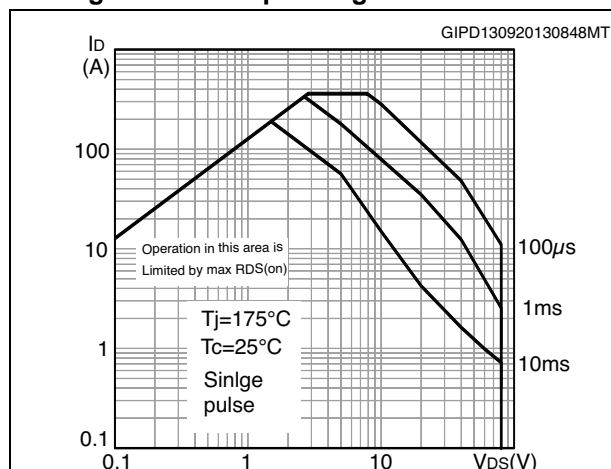
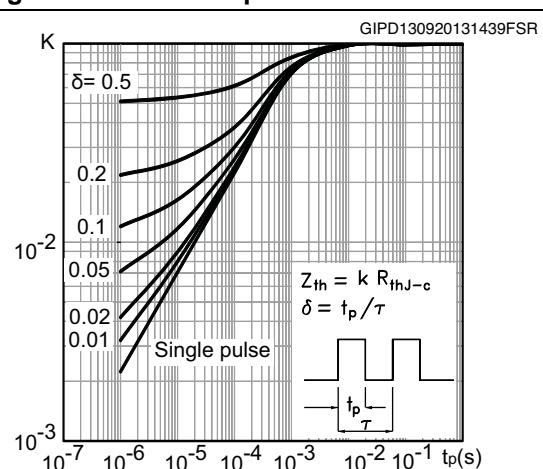
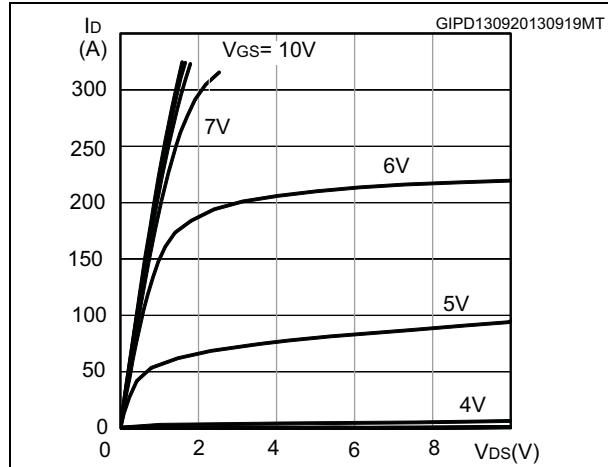
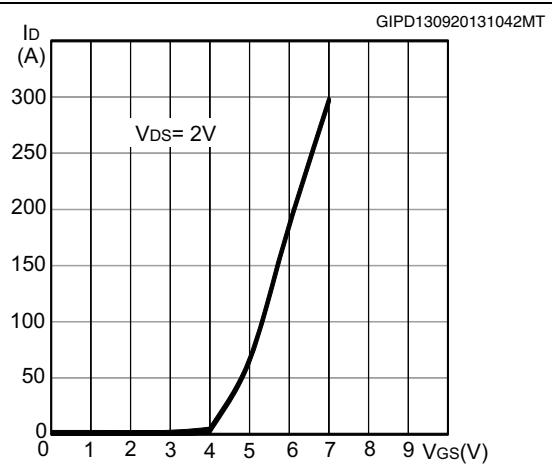
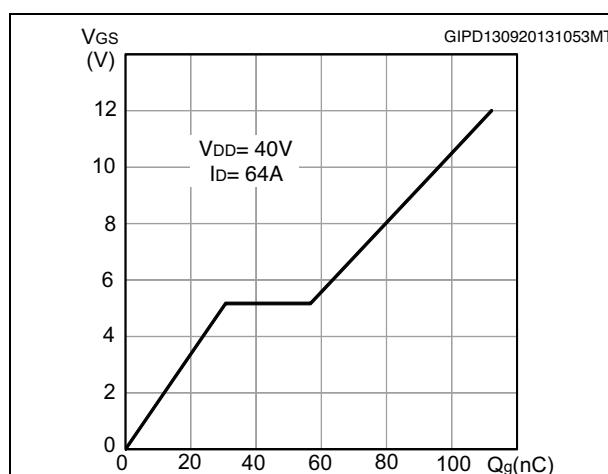
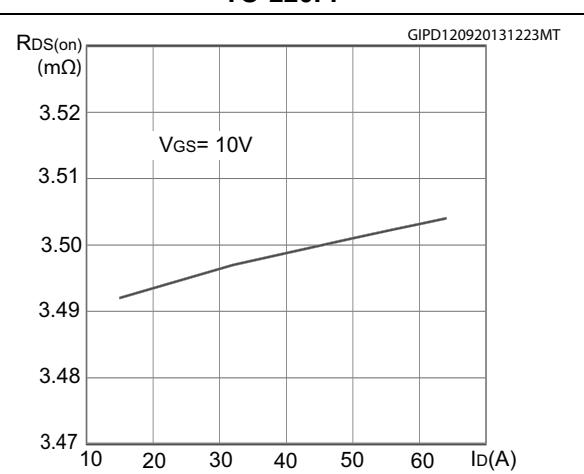
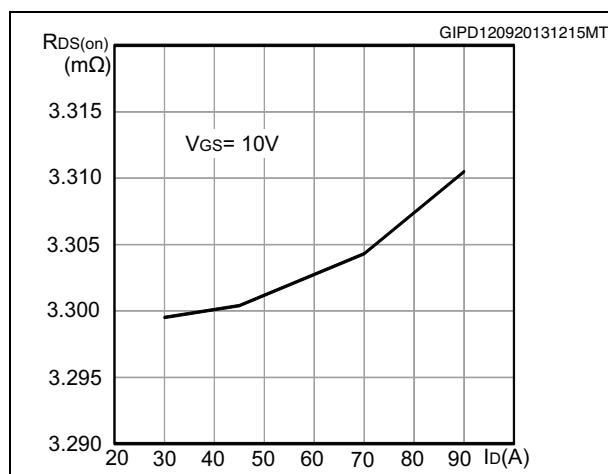
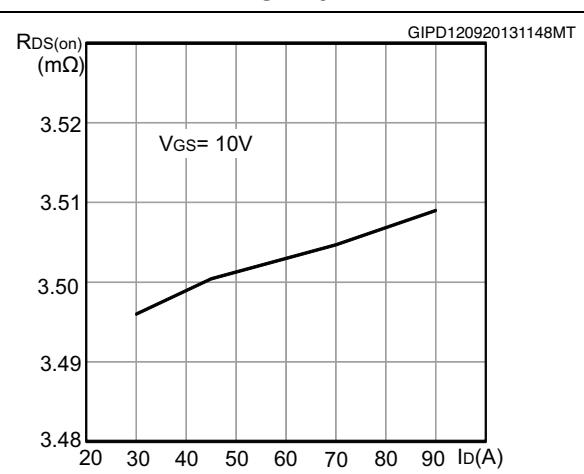
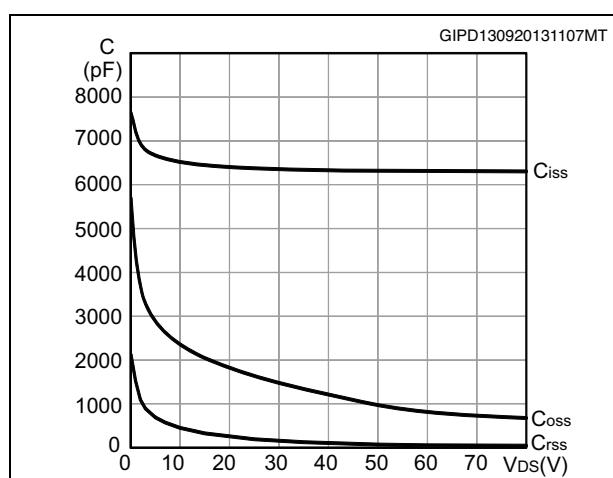
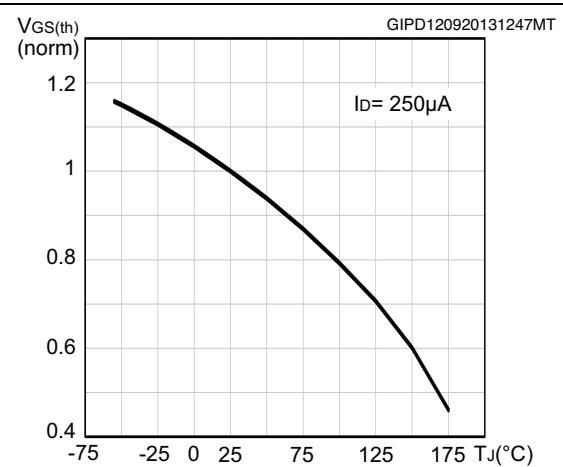
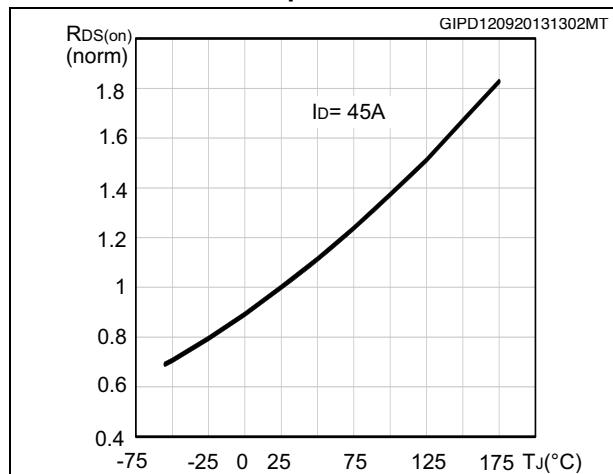
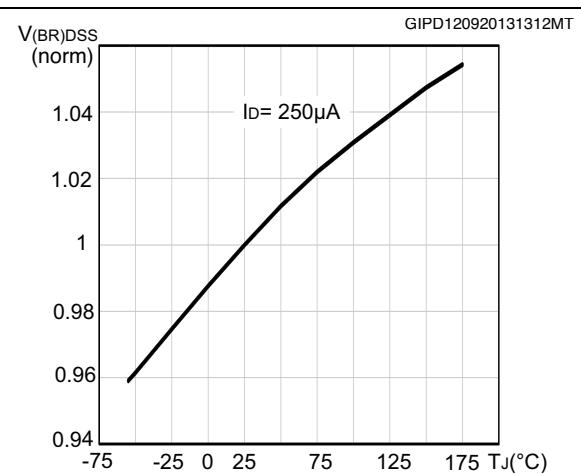
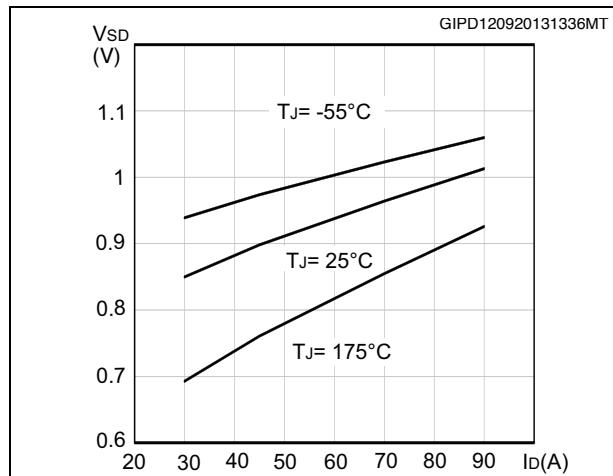
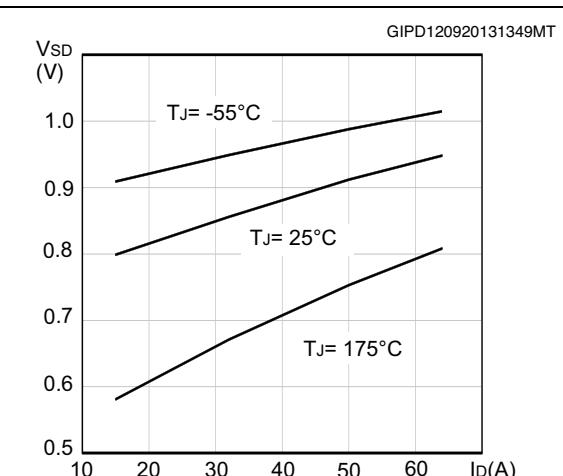


Figure 7. Thermal impedance for TO-220

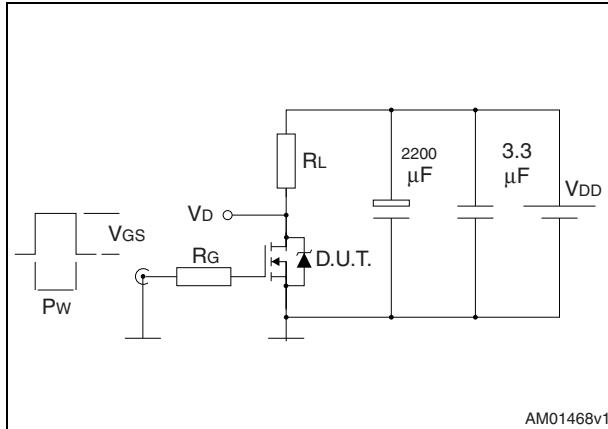


**Figure 8. Output characteristics****Figure 9. Transfer characteristics****Figure 10. Gate charge vs gate-source voltage****Figure 11. Static drain-source on-resistance for TO-220FP****Figure 12. Static drain-source on-resistance for H<sup>2</sup>PAK-2****Figure 13. Static drain-source on-resistance for TO-220**

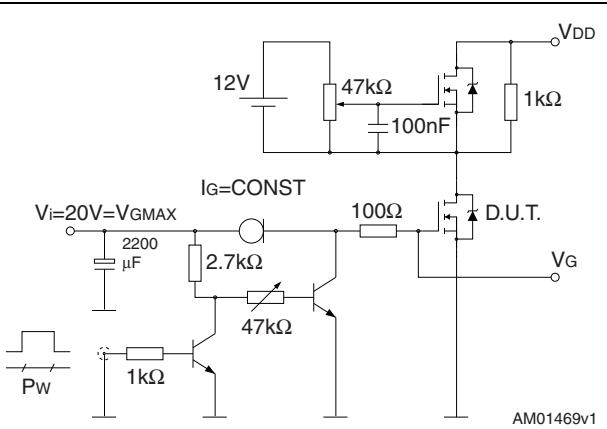
**Figure 14. Capacitance variations****Figure 15. Normalized gate threshold voltage vs temperature****Figure 16. Normalized on-resistance vs temperature****Figure 17. Normalized V(BR)DSS vs temperature****Figure 18. Source-drain diode forward characteristics for H<sup>2</sup>PAK-2 and TO-220****Figure 19. Source-drain diode forward characteristics for TO-220FP**

### 3 Test circuits

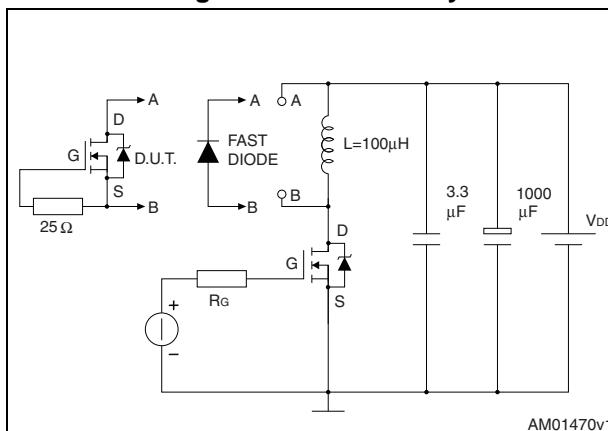
**Figure 20. Switching times test circuit for resistive load**



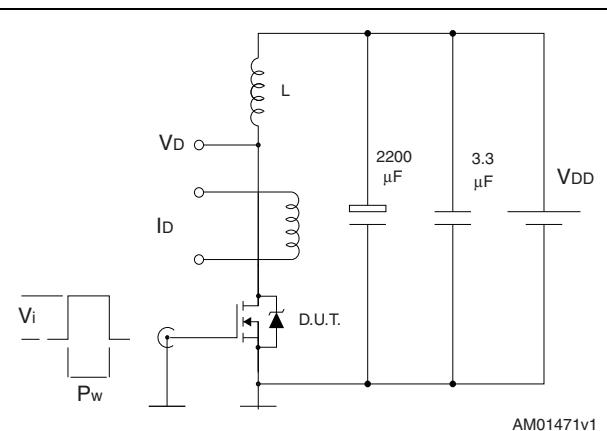
**Figure 21. Gate charge test circuit**



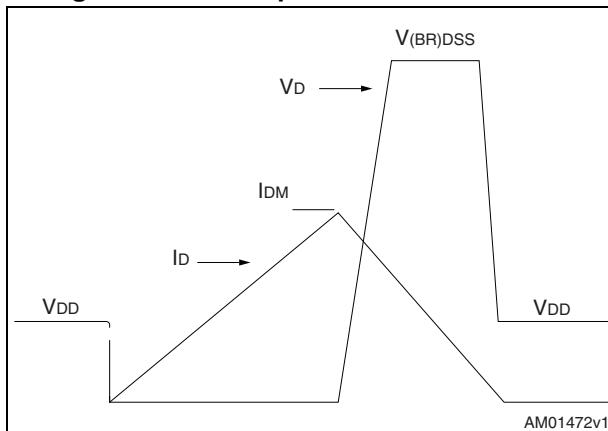
**Figure 22. Test circuit for inductive load switching and diode recovery times**



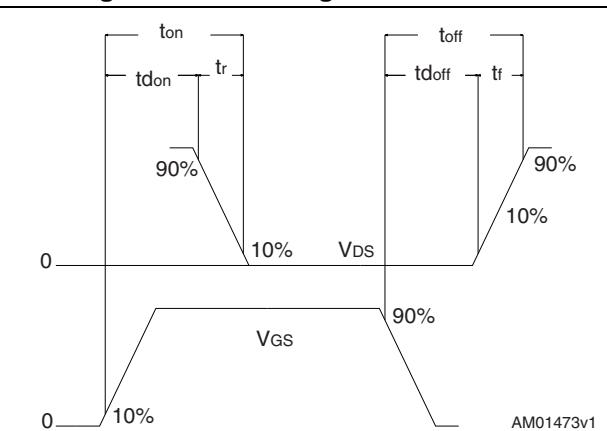
**Figure 23. Unclamped inductive load test circuit**



**Figure 24. Unclamped inductive waveform**



**Figure 25. Switching time waveform**



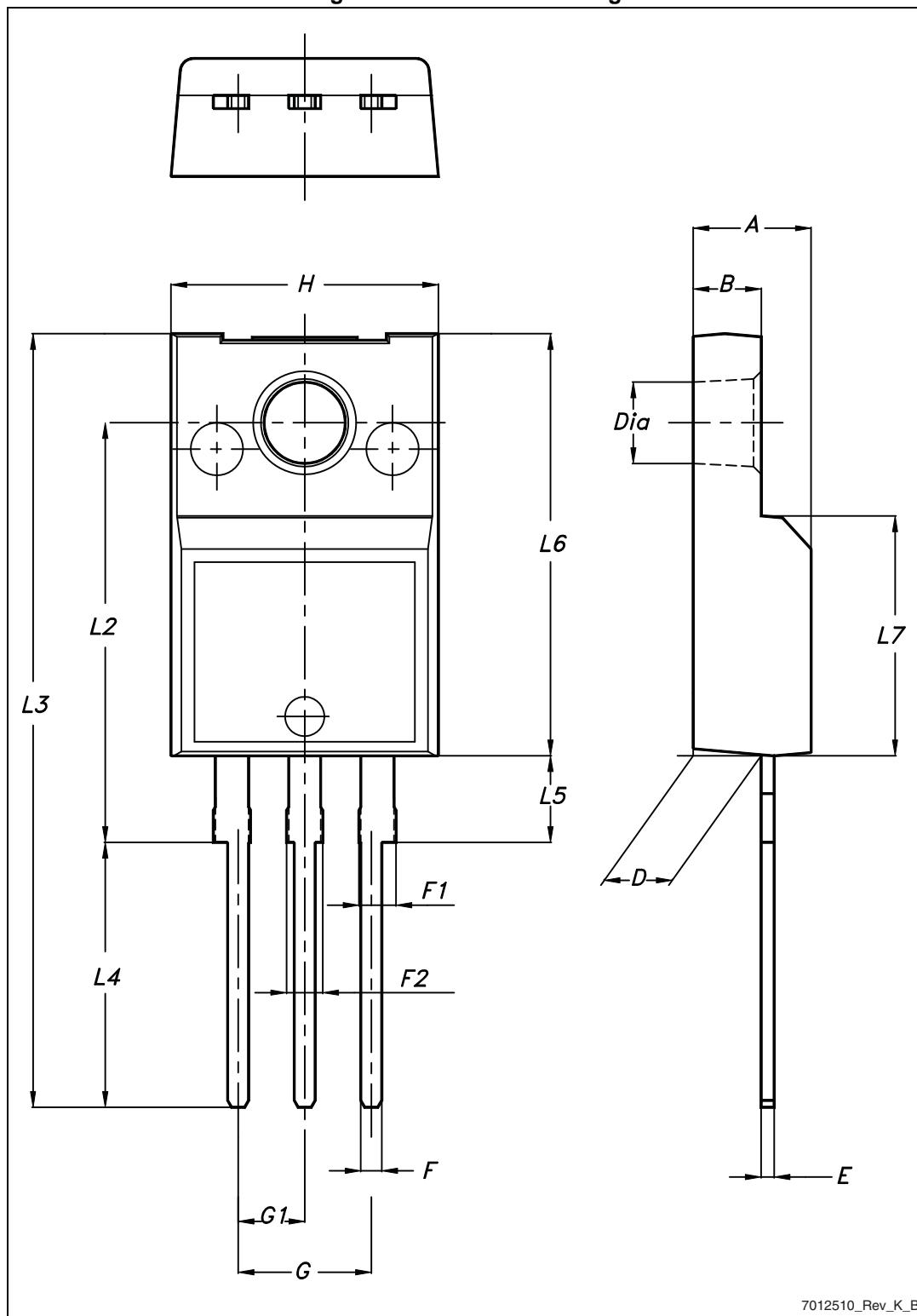
## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
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**Table 8. TO-220FP mechanical data**

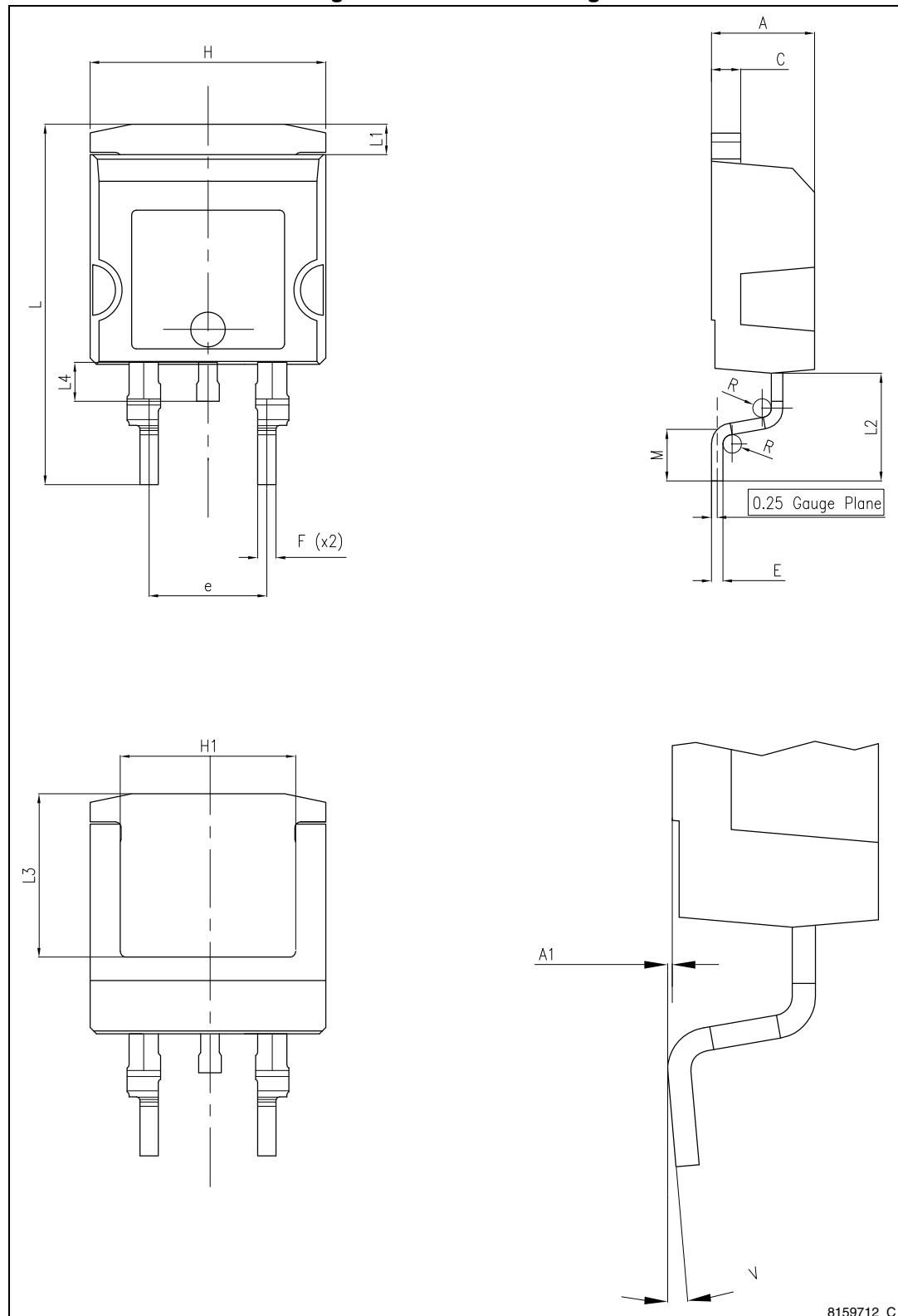
Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.60
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.40		2.7
H	10		14
L2		16	10.4
L3	28.6		
L4	9.8		30.6
L5	2.9		10.6
L6	15.9		3.6
L7	9		16.4
Dia	3		3.2

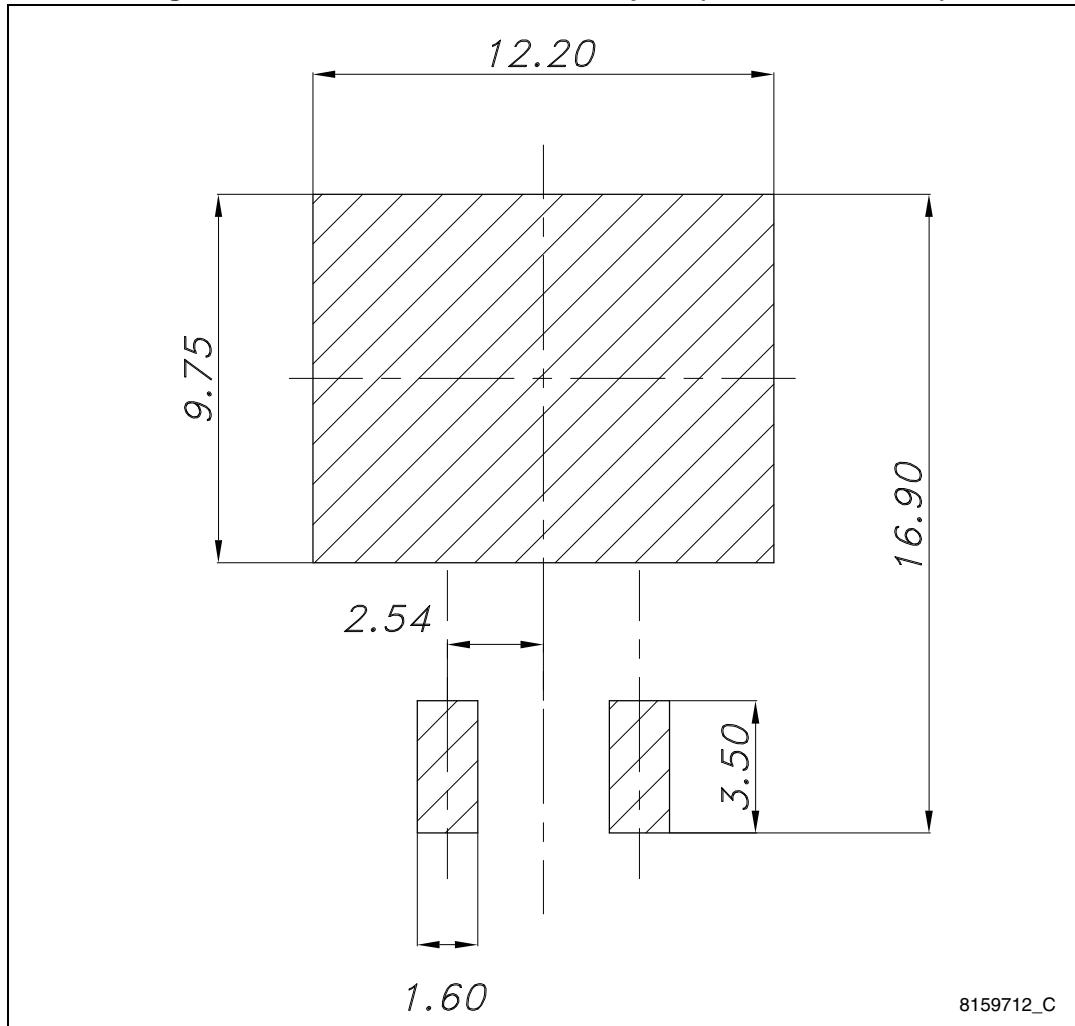
Figure 26. TO-220FP drawing



**Table 9. H<sup>2</sup>PAK-2 mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.30		4.80
A1	0.03		0.20
C	1.17		1.37
e	4.98		5.18
E	0.50		0.90
F	0.78		0.85
H	10.00		10.40
H1	7.40		7.80
L	15.30		15.80
L1	1.27		1.40
L2	4.93		5.23
L3	6.85		7.25
L4	1.5		1.7
M	2.6		2.9
R	0.20		0.60
V	0°		8°

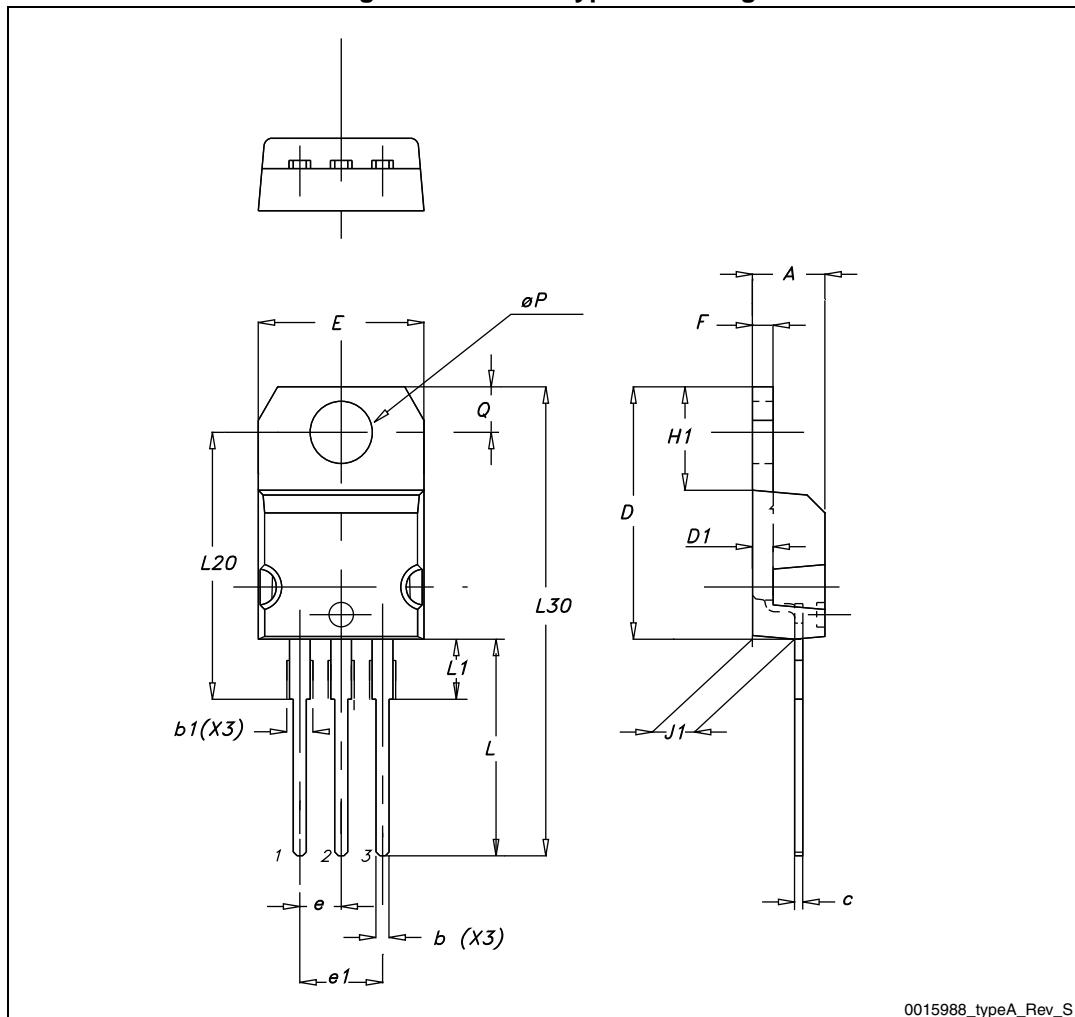
Figure 27. H<sup>2</sup>PAK-2 drawing

**Figure 28. H<sup>2</sup>PAK-2 recommended footprint (dimensions in mm)**

**Table 10. TO-220 type A mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

Figure 29. TO-220 type A drawing



## 5 Packaging mechanical data

Table 11. H<sup>2</sup>PAK-2 tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1		Base qty	1000
P2	1.9	2.1		Bulk qty	1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Figure 30. Tape dimension

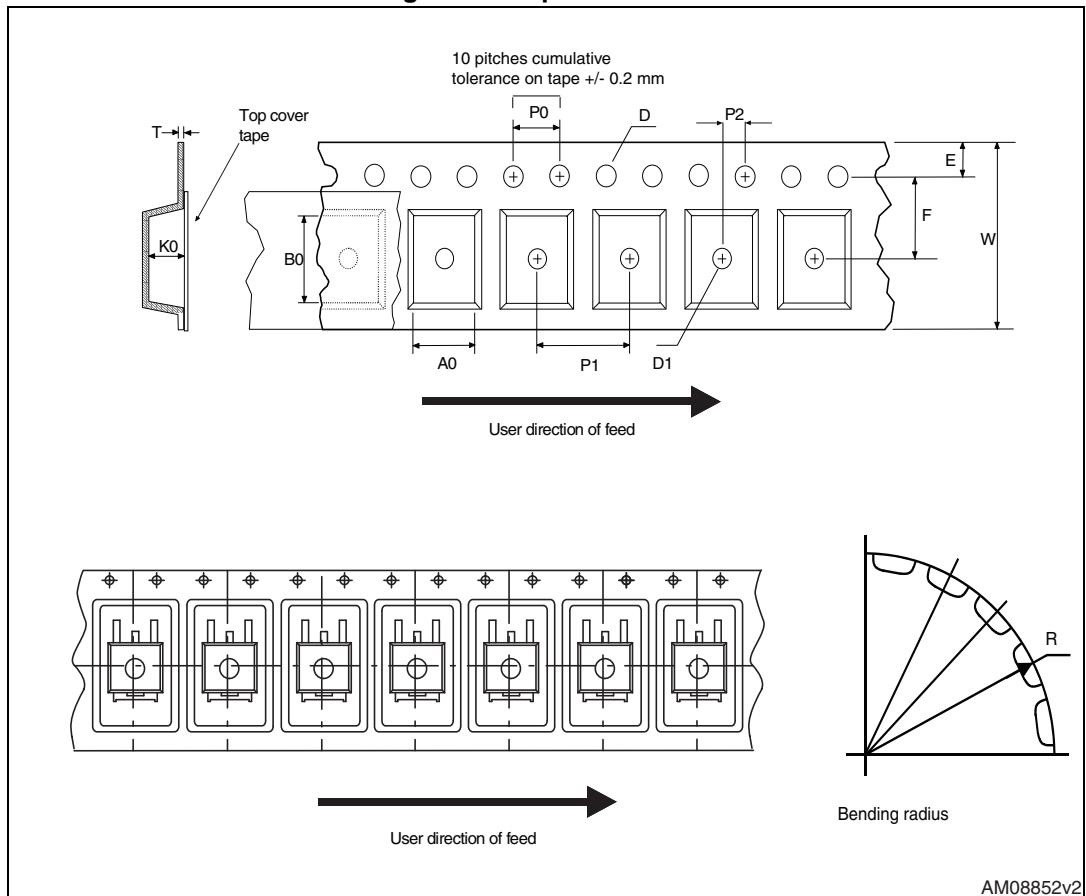
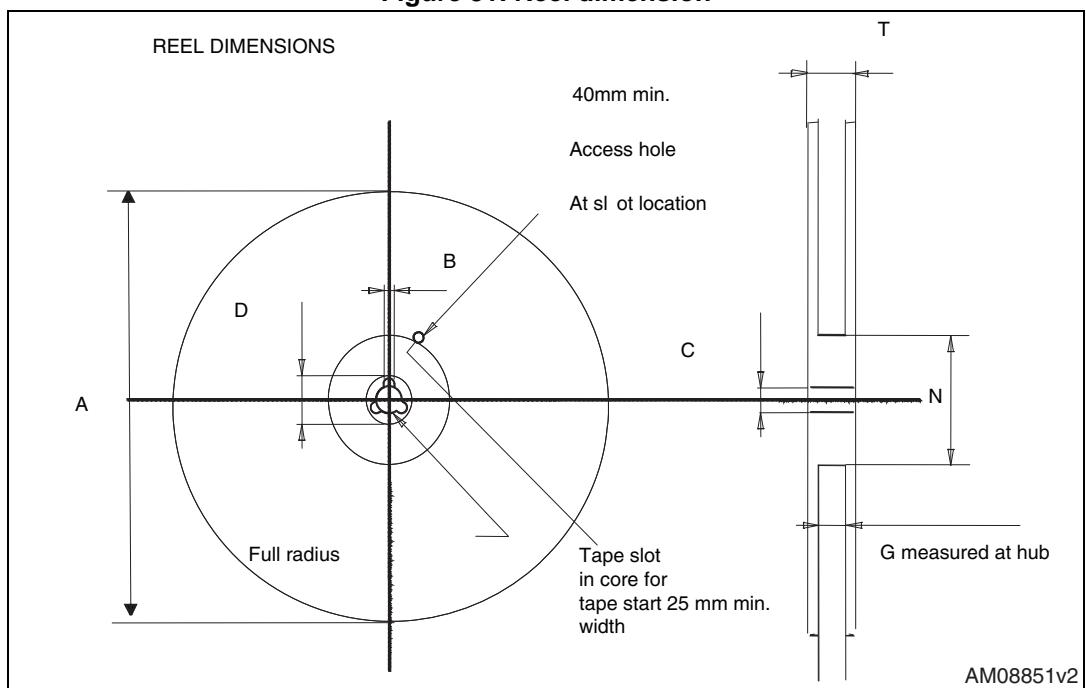


Figure 31. Reel dimension



## 6 Revision history

**Table 12. Document revision history**

Date	Revision	Changes
18-Sep-2013	1	First release.

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